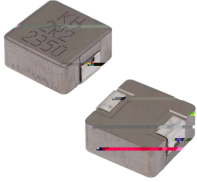


MDSA Series

SMD Low Profile High Current Molded Inductor

Size 1360



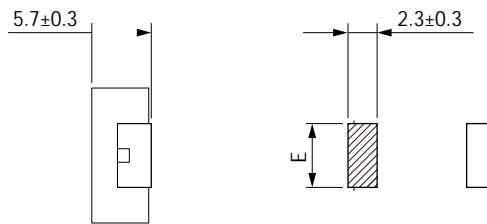
FEATURES

-
- Capable of corresponding high frequency
- Low loss realized with low DCR
- High performance (Isat) realized by metal dust core
-
- 100% Lead(Pb)-Free and RoHS compliant
-
-
-

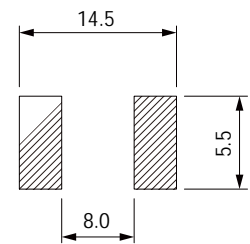
APPLICATION

-
-
-

Dimensions: [mm]



Land Pattern: [mm]



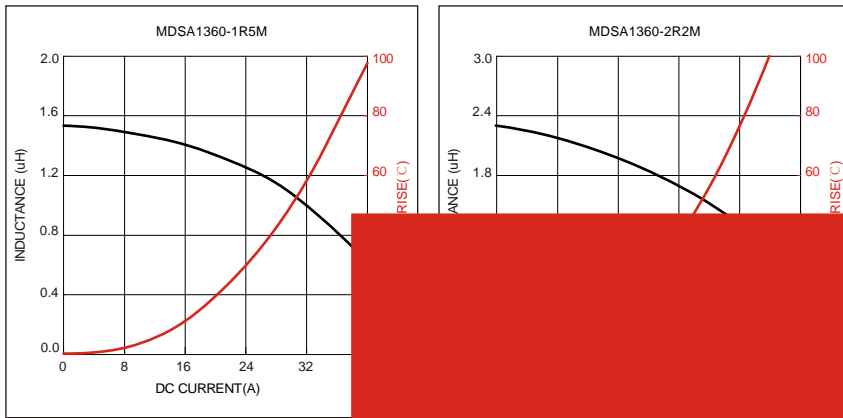
Electrical Properties:

Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Current Typ. (A)	DC Resistance Typ.	DC Resistance Max.	E
MDSA1360-1R5M		±20%	27.0	31.0	3.00	3.50	4.0±0.3
MDSA1360-2R2M		±20%	24.0	27.0	4.00	4.70	4.7±0.3
MDSA1360-3R3M	3.30	±20%	20.0	27.0	5.70	7.00	4.7±0.3
MDSA1360-4R7M	4.70	±20%	18.0	22.0	7.80	9.20	4.7±0.3
MDSA1360-8R2M	8.20	±20%	13.0	16.0	14.0	17.0	4.7±0.3
MDSA1360-100M	10.0	±20%	11.5	15.5	16.8	20.0	4.7±0.3
MDSA1360-150M	15.0	±20%	9.5	9.5	25.0	30.0	4.7±0.3
MDSA1360-220M	22.0	±20%	7.8	8.8	32.0	38.8	4.7±0.3
MDSA1360-330M	33.0	±20%	6.6	7.6	57.0	69.0	4.7±0.3
MDSA1360-470M	47.0	±20%	5.0	6.5	78.0	90.0	4.7±0.3

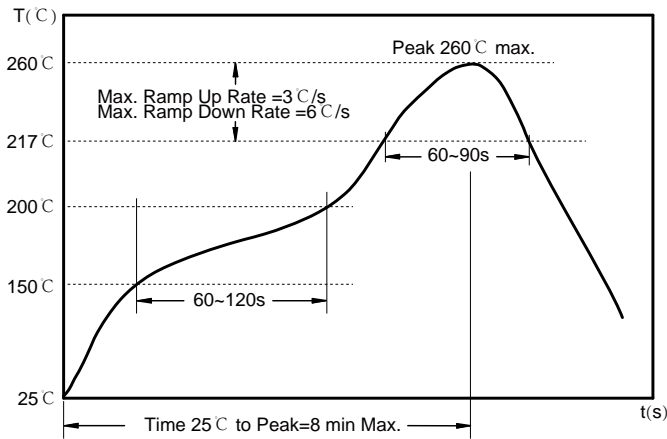
Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is $\Delta T=40^{\circ}\text{C}$

Typical Electrical Characteristics:



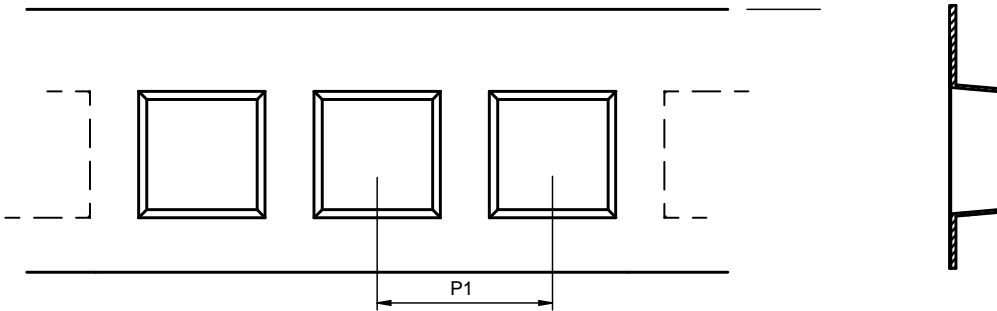
Soldering Reflow:



Preheat condition: 150 ~200°C / 60~120 sec.
 Allowed time above 217°C: 60~90 sec.
 Max temperature: 260°C.
 Max time at max temperature: 10 sec.
 Allowed Reflow time: 2x max.

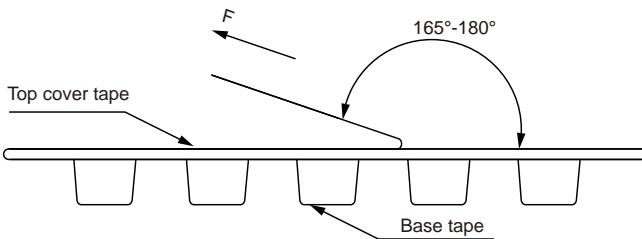
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
? 6E3#%("	#%~#f "ž#	#&ž' f "ž#	#ž f "ž#	&ž' f "ž#	#(ž' f "ž#	\$&ž' f "ž%	(ž/f "ž#	#ž' f "ž#	"ž" f "ž'

Peel force of top cover tape:



FZWbWVYadJWaXfab UahWifSbWeZS^TWfWfi VWV "ž# fa #ž%@

Product Marking:

? Sd] [Y	=: ŁBd[f[Y ;` VgUfS` UWfi
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